NICHIA CORPORATION SPECIFICATIONS FOR WHITE LED

# PART NO. NF2W757GRT-V4

- Pb-free Reflow Soldering Application
- ESD Withstand Voltage (HBM) Class 3B
- RoHS Compliant



# **SPECIFICATIONS**

(1) Absolute Maximum Ratings

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	${ m I}_{\sf F}$	200	mA
Pulse Forward Current	${ m I}_{\sf FP}$	400	mA
ESD Withstand Voltage (HBM)	$V_{ESD}$	8	kV
Allowable Reverse Current	${ m I}_{\sf R}$	85	mA
Power Dissipation	P <sub>D</sub>	1.32	W
Operating Temperature	$T_{opr}$	-40~100	°C
Storage Temperature	$T_{stg}$	-40~100	°C
Junction Temperature	Tı	120	°C

- \* Absolute Maximum Ratings at T<sub>J</sub>=25°C.
- \*  $I_{\text{FP}}$  conditions with pulse width  $\leq\!10\text{ms}$  and duty cycle  $\leq\!10\%.$
- \* For  $I_{\text{F}}$  and  $I_{\text{FP}}$ , see the "DERATING CHARACTERISTICS" of this specification.
- \* HBM ESD Component Classification Level of the LEDs: Class 3B For more details, see ANSI/ESDA/JEDEC JS-001.

(2) Initial Electrical/Optical Characteristics

2) Illitiai Electrical/Optic	ai Characteristics						
It	em	Symbol	Condition	Тур	Max	Unit	
Forward Voltage		$V_{F}$	I <sub>F</sub> =150mA	6.2	-	V	
R70	<u>_</u>		I <sub>F</sub> =150mA	158	-		
R8000	Luminous Flux	$\Phi_{\nu}$	I <sub>F</sub> =150mA	144	-	lm	
R9050	(Chromaticity Coordinate1)		I <sub>F</sub> =150mA	126	-		
	X		I <sub>F</sub> =150mA	0.4338	-		
Chromaticity Coordinate1	у	i	I <sub>F</sub> =150mA	0.4030	-	_	
R70			I <sub>F</sub> =150mA	164	-		
R8000	Luminous Flux	Фи	I <sub>F</sub> =150mA	153	-	lm	
R9050	(Chromaticity Coordinate2)		I <sub>F</sub> =150mA	136	-		
Character to Constitution	X		I <sub>F</sub> =150mA	0.3447	-	-	
Chromaticity Coordinate2	у	-	I <sub>F</sub> =150mA	0.3553	-		
Thermal Resistance		Rejs	-	11	17	°C/W	

- \* Characteristics at  $T_1=25$ °C and measured in pulse mode.
- \* Optical Characteristics as per CIE 127:2007 standard.
- \* Chromaticity Coordinates as per CIE 1931 Chromaticity Chart.
- \*  $R_{\theta JS}$  is measured using the Dynamic Mode detailed in JESD51-1.
- \*  $R_{\theta JS}$  is the thermal resistance from the junction to the  $T_S$  measurement point. (Test board: FR4 board thickness=1.6mm, copper layer thickness=0.07mm)
- \* The Max value for the  $R_{\mbox{\scriptsize BJS}}$  is for reference purposes only.

# **RANKS**

Item	Rank		Condition	Min	Max	Unit	
Forward Voltage	-		$I_F=150mA$	5.8	6.6	V	
	P21			171.2	204.0		
	P20			144.0	171.2		
	P19			121.1	144.0		
Luminous Flux	P18		$I_F=150mA$	101.8	121.1	lm	
	P17			85.6	101.8		
	P16			72.0	85.6		
	P15			60.5	72.0		
	R70	Ra		70	-		
	D0000	Ra		80	-		
Color Rendering Index	R8000	R <sub>9</sub>	$I_F=150mA$	>0	-	-	
		Ra		90	-		
	R9050	R <sub>9</sub>		50	-		

Color Ranks(I<sub>F</sub>=150mA)

The color ranks have chromaticity ranges within 3-step MacAdam ellipse.

		Rank	Rank	Rank	Rank	Rank	Rank
		sm1836c	sm203	sm223	sm243	sm253	sm273
Color Temperature (Unit: K)	Тср	1800	2000	2200	2400	2500	2700
	Х	0.5433	0.5270	0.5018	0.4829	0.4806	0.4578
Center Point	у	0.4087	0.4130	0.4153	0.4144	0.4141	0.4101
Minor Axis	а	0.003963	0.003978	0.004002	0.004023	0.004029	0.004056
Major Axis	b	0.007047	0.007062	0.007206	0.007479	0.007515	0.007872
Ellipse Rotation Angle	Ф	133.5	-43.56	-39.89	-37.58	-37.58	-36.05

		Rank sm303	Rank sm353	Rank sm403	Rank sm453	Rank sm503	Rank sm573
Color Temperature (Unit: K)	Тср	3000	3500	4000	4500	5000	5700
	х	0.4338	0.4073	0.3818	0.3611	0.3447	0.3287
Center Point	у	0.4030	0.3917	0.3797	0.3658	0.3553	0.3417
Minor Axis	а	0.004107	0.004098	0.004071	0.003852	0.003555	0.003087
Major Axis	b	0.008391	0.008796	0.009282	0.009009	0.008418	0.007809
Ellipse Rotation Angle	Ф	-36.00	-35.47	-35.95	-34.33	-31.78	-31.56

		Rank
		sm653
Color Temperature (Unit: K)	T <sub>CP</sub>	6500
	Х	0.3123
Center Point	У	0.3282
Minor Axis	a	0.002709
Major Axis	b	0.006561
Fllipse Rotation Angle	Φ	-32.35

The color ranks have chromaticity ranges within 5-step MacAdam ellipse.

		Rank	Rank	Rank	Rank	Rank	Rank		
		sm1856ca	sm1856cb	sm1856cc	sm1856cd	sm1856ce	sm1856cf		
Color Temperature (Unit: K)	Тср		1800						
Cautau Daiat	х	0.5433							
Center Point	У	0.4087							
Minor Axis	a			0.00	6605				
Major Axis	b	0.011745							
Ellipse Rotation Angle	Ф			13:	3.5				

		Rank sm2050a	Rank sm2050b	Rank sm2050c	Rank sm2050d	Rank sm2050e	Rank sm2050f		
Color Temperature (Unit: K)	Тср		2000						
Contra Baird	х	0.5270							
Center Point	у	0.4130							
Minor Axis	a			0.00	6630				
Major Axis	b	0.011770							
Ellipse Rotation Angle	Φ		-43.56						

		Rank sm2250a	Rank sm2250b	Rank sm2250c	Rank sm2250d	Rank sm2250e	Rank sm2250f		
Color Temperature (Unit: K)	T <sub>CP</sub>		2200						
C. I. D. I	Х	0.5018							
Center Point	У	0.4153							
Minor Axis	a		0.006670						
Major Axis	b	0.012010							
Ellipse Rotation Angle	Ф		-39.89						

		Rank sm2450a	Rank sm2450b	Rank sm2450c	Rank sm2450d	Rank sm2450e	Rank sm2450f		
Color Temperature (Unit: K)	Тср		2400						
Colo Bill	х	0.4829							
Center Point	У	0.4144							
Minor Axis	а			0.00	6705				
Major Axis	b	0.012465							
Ellipse Rotation Angle	Φ		-37.58						

		Rank sm2550a	Rank sm2550b	Rank sm2550c	Rank sm2550d	Rank sm2550e	Rank sm2550f		
Color Temperature (Unit: K)	Тср		2500						
College Bride	х	0.4806							
Center Point	У	0.4141							
Minor Axis	a			0.00	6715				
Major Axis	b	0.012525							
Ellipse Rotation Angle	Ф		-37.58						

		Rank sm2750a	Rank sm2750b	Rank sm2750c	Rank sm2750d	Rank sm2750e	Rank sm2750f			
Color Temperature (Unit: K)	Тср		2700							
C. I. B. I.	х	0.4578								
Center Point	У	0.4101								
Minor Axis	a			0.00	6760					
Major Axis	b	0.013120								
Ellipse Rotation Angle	Ф			-36	5.05					

		Rank sm3050a	Rank sm3050b	Rank sm3050c	Rank sm3050d	Rank sm3050e	Rank sm3050f			
Color Temperature (Unit: K)	Тср		3000							
Contraction	х	0.4338								
Center Point	у	0.4030								
Minor Axis	а	0.006845								
Major Axis	b	0.013985								
Ellipse Rotation Angle	Φ	-36.00								

		Rank sm3550a	Rank sm3550b	Rank sm3550c	Rank sm3550d	Rank sm3550e	Rank sm3550f			
Color Temperature (Unit: K)	T <sub>CP</sub>		3500							
	Х	0.4073								
Center Point	У	0.3917								
Minor Axis	а	0.006830								
Major Axis	b	0.014660								
Ellipse Rotation Angle	Ф	-35.47								

		Rank sm4050a	Rank sm4050b	Rank sm4050c	Rank sm4050d	Rank sm4050e	Rank sm4050f			
Color Temperature (Unit: K)	Тср		4000							
Colo Bill	х	0.3818								
Center Point	У	0.3797								
Minor Axis	а	0.006785								
Major Axis	b	0.015470								
Ellipse Rotation Angle	Φ	-35.95								

		Rank sm4550a	Rank sm4550b	Rank sm4550c	Rank sm4550d	Rank sm4550e	Rank sm4550f			
Color Temperature (Unit: K)	Тср		4500							
C. I. D. I	Х	0.3611								
Center Point	У	0.3658								
Minor Axis	a	0.006420								
Major Axis	b	0.015015								
Ellipse Rotation Angle	Ф	-34.33								

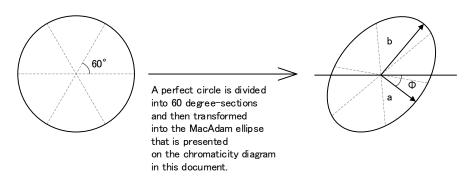
		Rank sm5050a	Rank sm5050b	Rank sm5050c	Rank sm5050d	Rank sm5050e	Rank sm5050f			
Color Temperature (Unit: K)	Тср		5000							
C. I. B. I.	х	0.3447								
Center Point	у	0.3553								
Minor Axis	a	0.005925								
Major Axis	b	0.014030								
Ellipse Rotation Angle	Ф	-31.78								

		Rank sm5750a	Rank sm5750b	Rank sm5750c	Rank sm5750d	Rank sm5750e	Rank sm5750f			
Color Temperature (Unit: K)	Тср		5700							
	х	0.3287								
Center Point	у	0.3417								
Minor Axis	a	0.005145								
Major Axis	b	0.013015								
Ellipse Rotation Angle	Ф	-31.56								

		Rank sm6550a	Rank sm6550b	Rank sm6550c	Rank sm6550d	Rank sm6550e	Rank sm6550f			
Color Temperature (Unit: K)	$T_{CP}$		6500							
Color	Х	0.3123								
Center Point	у		0.3282							
Minor Axis	а	0.004515								
Major Axis	b	0.010935								
Ellipse Rotation Angle	Ф	-32.35								

- \* Ranking at  $T_1=25$ °C and measured in pulse mode.
- \* Forward Voltage Tolerance: ±0.07V
- \* Luminous Flux Tolerance:  $\pm 5\%$
- \* Color Rendering Index  $R_a$  Tolerance:  $\pm 1.5$
- \* Color Rendering Index R<sub>9</sub> Tolerance: ±3
- \* Chromaticity Coordinate Tolerance: ±0.003
- st LEDs from the above ranks will be shipped. The rank combination ratio per shipment will be decided by Nichia.

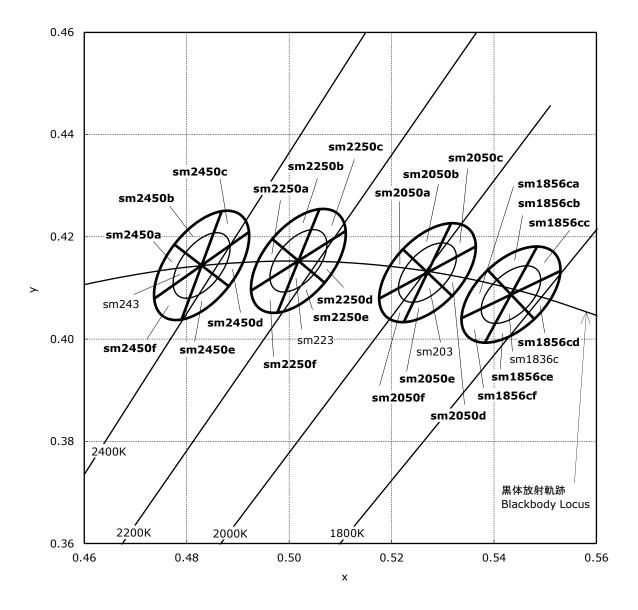
### Definition of the MacAdam ellipse ranks:

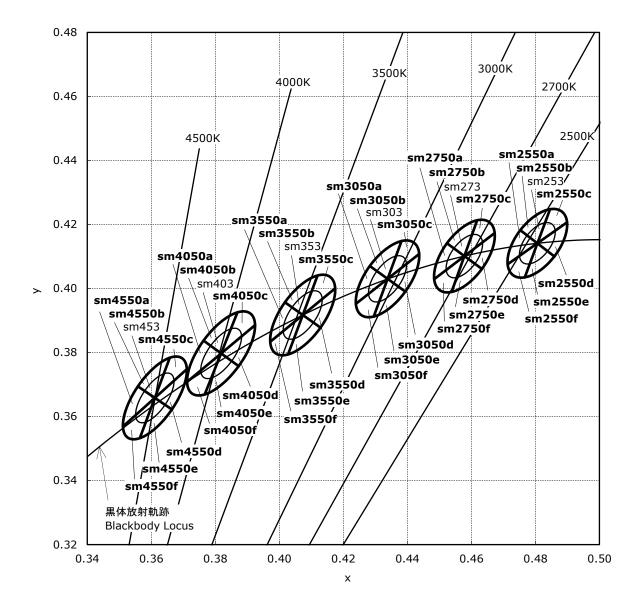


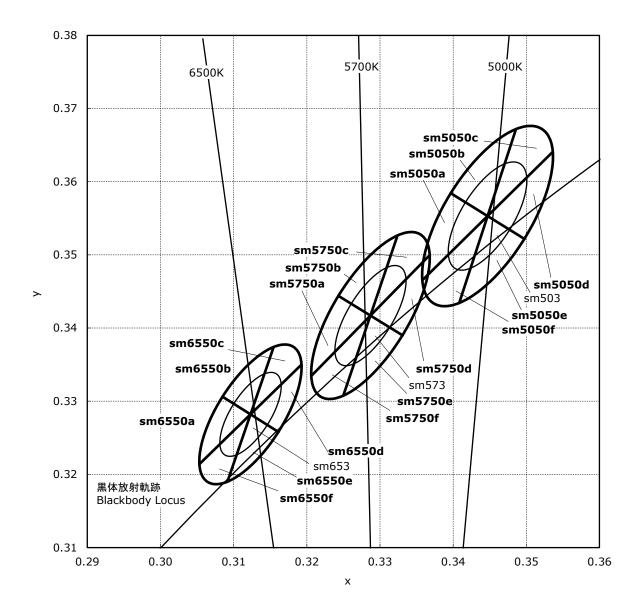
Luminous Flux Ranks by Color Rank, Color Rendering Index Rank

uminous Flux Ranks by Color Rank, Color Rendering Index Rank								
	anking by							
	nous Flux							
Ranking by		P15	P16	P17	P18	P19	P20	P21
Color Coordinates,								
Color Rendering Index								
	R70							
sm1836c,sm1856ca,sm1856cb,sm1856cc,sm1856cd,sm1856ce,								
sm1856cf								
	R9050							
	R70							
sm203,sm2050a,sm2050b,sm2050c,sm2050d,sm2050e,sm2050f								
\$111203,511120300a,511120300b,511120300c,511120300c,511120301	R8000,							
	R9050							
	R70							
sm223,sm2250a,sm2250b,sm2250c,sm2250d,sm2250e,sm2250f	R8000							
	R9050							
242 2450 2450 2450 2450 2450	BOOFO							
sm243,sm2450a,sm2450b,sm2450c,sm2450d,sm2450e,sm2450f	R9050							
	R70							
sm253,sm2550a,sm2550b,sm2550c,sm2550d,sm2550e,sm2550f	R8000							
5111233,511123300a,511123300b,511123300a,511123300e,511123301	Koooo							
	R9050							
	R70							
	100							
sm273,sm2750a,sm2750b,sm2750c,sm2750d,sm2750e,sm2750f	R8000							
	R9050							
	R70							
sm303,sm3050a,sm3050b,sm3050c,sm3050d,sm3050e,sm3050f								
	R8000,							
	R9050							
	R70,							
sm353,sm3550a,sm3550b,sm3550c,sm3550d,sm3550e,sm3550f,	R8000							
sm403,sm4050a,sm4050b,sm4050c,sm4050d,sm4050e,sm4050f,								
sm453,sm4550a,sm4550b,sm4550c,sm4550d,sm4550e,sm4550f	R9050							

	nking by ous Flux							
Ranking by		P15	P16	P17	P18	P19	P20	P21
Color Coordinates,								
Color Rendering Index								
sm503,sm5050a,sm5050b,sm5050c,sm5050d,sm5050e,sm5050f,	R70, R8000							
sm573,sm5750a,sm5750b,sm5750c,sm5750d,sm5750e,sm5750f, sm653,sm6550a,sm6550b,sm6550c,sm6550d,sm6550e,sm6550f	R9050							





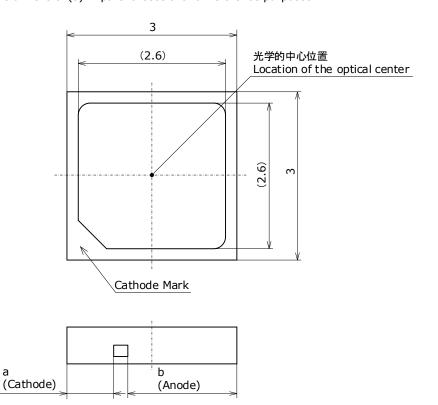


# **OUTLINE DIMENSIONS**

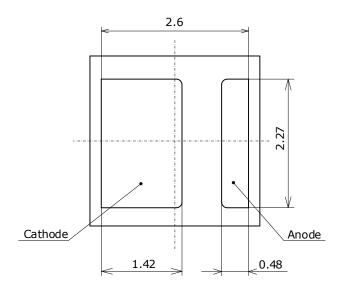
\* 本製品はRoHS指令に適合しております。 This product complies with RoHS Directive.

\* 括弧で囲まれた寸法は参考値です。 The dimension(s) in parentheses are for reference purposes. Part No. NF2W757GR-Vx No. STS-DA7-14308B

(単位 Unit: mm, 公差 Tolerance: ±0.2)

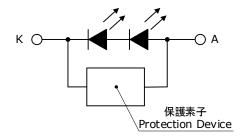






項目 Item	内容 Description
パッケージ材質 Package Materials	耐熱性ポリマー Heat-Resistant Polymer
封止樹脂材質 Encapsulating Resin Materials	シリコーン樹脂 (拡散剤+蛍光体入り) Silicone Resin (with diffuser and phosphor)
電極材質 Electrodes Materials	銅合金+銀メッキ Ag-plated Copper Alloy
質量 Weight	0.018g(TYP)

- \* バリは寸法に含まないものとします。 Dimensions do not include mold flash.
- \* b>aとなる場合、aがカソード側です。
  The side with the smaller distance is the cathode.
  Example: b>a, then a is the side that has the cathode.



# **SOLDERING**

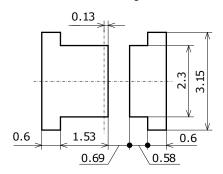
• Recommended Reflow Soldering Condition(Lead-free Solder)

:	Pre-heat 180 to 200°C	J.	260°CMax 10sec Max
/	120Sec Max	/	

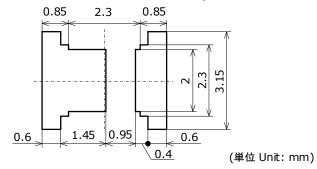
• Recommended Hand Soldering Condition

Temperature	350°C Max
Soldering Time	3sec Max

• Recommended Soldering Pad Pattern

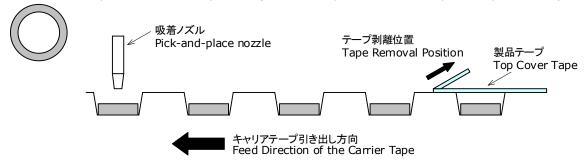


• Recommended Metal Solder Stencil Aperture

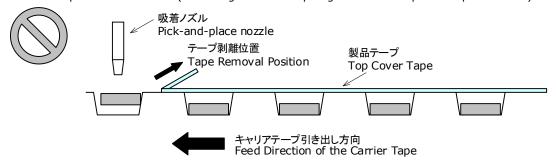


- \* This LED is designed to be reflow soldered to a PCB. If dip soldered, Nichia will not guarantee its reliability.
- \* Reflow soldering must not be performed more than twice. Hand soldering must not be performed more than once.
- \* When cooling the LEDs from the peak temperature a gradual cooling slope is recommended; do not cool the LEDs rapidly.
- \* During reflow soldering, the heat and atmosphere in the reflow oven may cause the optical characteristics to degrade. In particular, reflow soldering performed with an air atmosphere may have a greater negative effect on the optical characteristics than if a nitrogen atmosphere is used; Nichia recommends using a nitrogen reflow atmosphere.
- \* This LED uses a silicone resin for the encapsulating resin; the silicone resin is soft. If pressure is applied to the silicone resin, it may cause the resin to be damaged, chipped, delaminated and/or deformed. If the resin is damaged, chipped, delaminated and/or deformed, it may cause the wire to break causing a catastrophic failure (i.e. the LED not to illuminate) and/or reliability issues (e.g. the LED to corrode and/or to become dimmer, the color/directivity to change, etc.). Ensure that pressure is not applied to the encapsulating resin.
- \* Once the LEDs have been soldered to a PCB, it should not be repaired/reworked. If it must be done, using a double-head soldering iron is strongly recommended. Ensure that sufficient verification is performed prior to use to ensure that the repair/rework has not caused the LED characteristics to deteriorate.
- \* When soldering, do not apply stress to the LED while the LED is hot.
- \* When using an automatic pick-and-place machine, choose an appropriate nozzle for this LED. Using a pick-and-place nozzle with a smaller diameter than the size of the LED's emitting surface will cause damage to the emitting surface causing a catastrophic failure (i.e. the LED not to illuminate).

- \* If the top cover tape is removed right next to where the nozzle picks up the LEDs, regardless of whether the LEDs have been baked or not, it may cause the LED to be picked up incorrectly; it is recommended to remove the top cover tape further from where the nozzle picks up the LEDs. Ensure that there are no issues with the conditions when the nozzle picks up the LEDs.
  - Recommended Tape Removal Position(Removing the cover tape further from the pick-and-place nozzle)



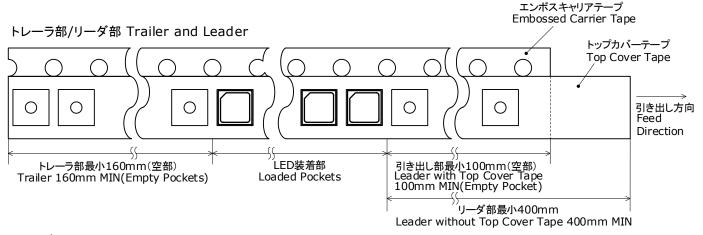
• Incorrect Tape Removal Position(Removing the cover tape right next to the pick-and-place nozzle)



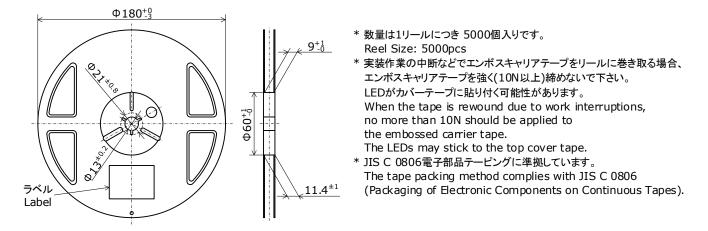
- \* Verify the setting conditions when the LEDs are mounted onto a PCB to ensure that the LEDs are mounted onto the PCB with the correct polarity. If the cathode mark is not able to be easily recognized with a visual inspection, check the back or side of the LED to determine the polarity.
- \* The soldering pad pattern above is a general recommendation for LEDs to be mounted without issues; if a high degree of precision is required for the chosen application (i.e. high-density mounting), ensure that the soldering pad pattern is optimized.
- \* Consider factors such as the reflow soldering temperature, hand soldering temperature, etc. when choosing the solder.
- \* When flux is used, it should be a halogen free flux. Ensure that the manufacturing process is not designed in a manner where the flux will come in contact with the LEDs.
- \* Ensure that there are no issues with the type and amount of solder that is being used.
- \* This LED has all the electrodes on the backside; solder connections will not be able to be seen nor confirmed by a normal visual inspection. Ensure that sufficient verification is performed on the soldering conditions prior to use to ensure that there are no issues.

# TAPE AND REEL DIMENSIONS

# アーピング部 Tape Part No. Nxxx757x No. STS-DA7-9622A (単位 Unit: mm) Cathode Mark 4 ± 0.1 4 ±



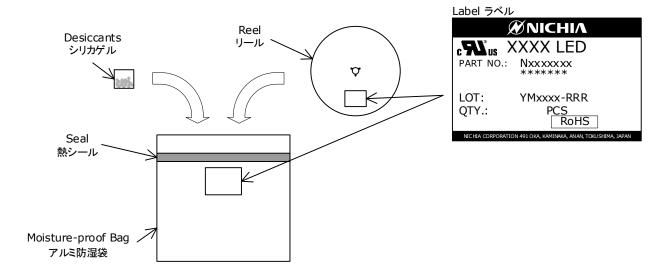
# リール部 Reel



# PACKAGING - TAPE & REEL

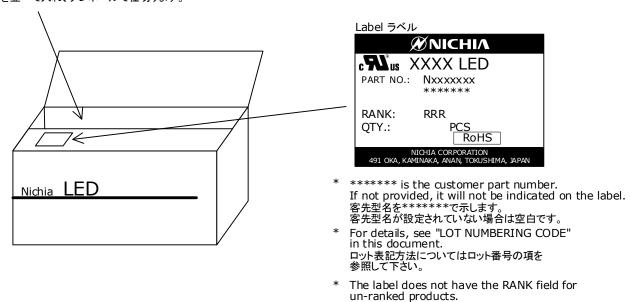
Reels are shipped with desiccants in heat-sealed moisture-proof bags. シリカゲルとともにリールをアルミ防湿袋に入れ、熱シールにより封をします。

Part No. Nxxxxxxx No. STS-DA7-4989C



 $\label{thm:proof-bags} \mbox{ Anomaly noise packed in cardboard boxes with corrugated partitions.}$ 

アルミ防湿袋を並べて入れ、ダンボールで仕切ります。



ランク分けがない場合はランク表記はありません。

- \* Products shipped on tape and reel are packed in a moisture-proof bag.
  They are shipped in cardboard boxes to protect them from external forces during transportation.
  本製品はテーピングしたのち、輸送の衝撃から保護するためダンボールで梱包します。
- \* Do not drop or expose the box to external forces as it may damage the products. 取り扱いに際して、落下させたり、強い衝撃を与えたりしますと、製品を損傷させる原因になりますので注意して下さい。
- \* Do not expose to water. The box is not water-resistant. ダンボールには防水加工がされておりませんので、梱包箱が水に濡れないよう注意して下さい。
- \* Using the original package material or equivalent in transit is recommended. 輸送、運搬に際して弊社よりの梱包状態あるいは同等の梱包を行って下さい。

# LOT NUMBERING CODE

Lot Number is presented by using the following alphanumeric code.

# YMxxxx - RRR

Y - Year

Year	Y
2024	0
2025	Р
2026	Q
2027	R
2028	S
2029	Т

Thereafter, a letter of the alphabet is assigned to each year in alphabetical order.

### M - Month

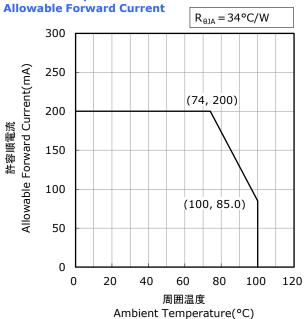
Month	М	Month	М	
1	1	7	7	
2	2	8	8	
3	3	9	9	
4	4	10	А	
5	5 5		В	
6	6	12	С	

xxxx-Nichia's Product Number

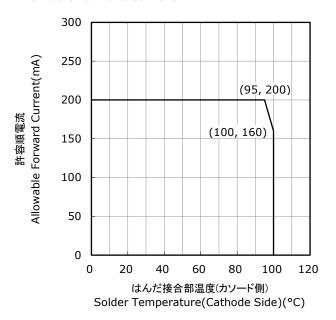
RRR-Ranking by Color Coordinates, Ranking by Luminous Flux, Ranking by Color Rendering Index

NF2x757GR-Vx 管理番号 No. STS-DA7-9908A

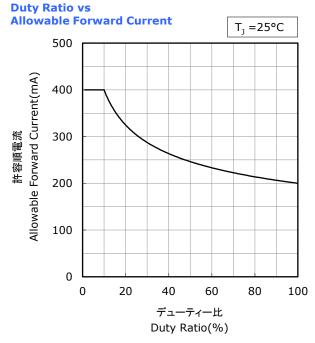
周囲温度-許容順電流特性 Ambient Temperature vs



はんだ接合部温度(カソード側)-許容順電流特性 Solder Temperature(Cathode Side) vs Allowable Forward Current



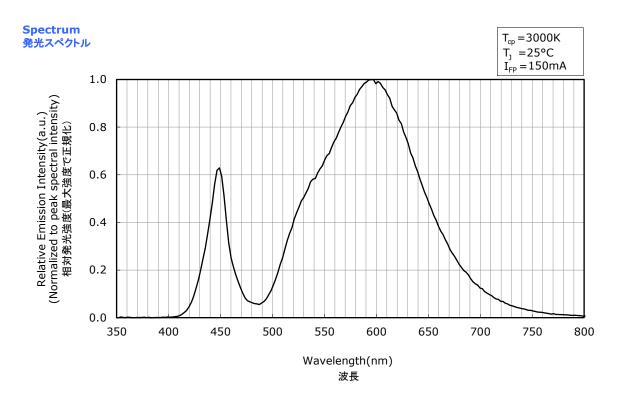
### デューティー比-許容順電流特性



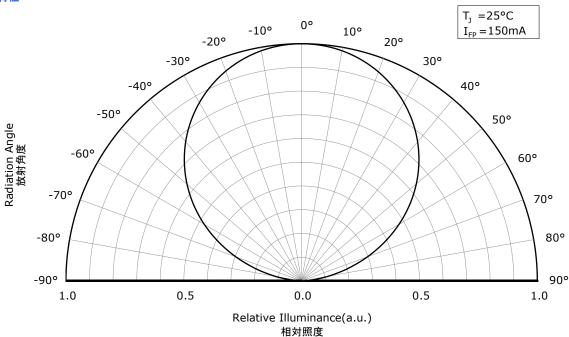
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-V4 No. STS-DA7-20364

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。





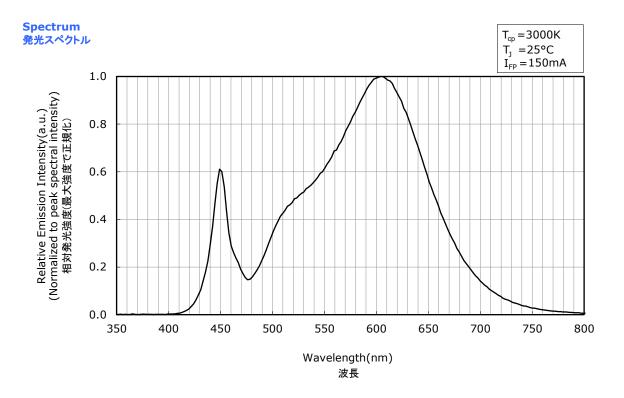


\* The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

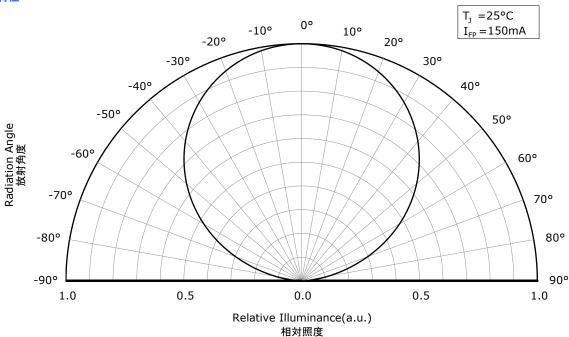
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14291A

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



### Directivity 指向特性

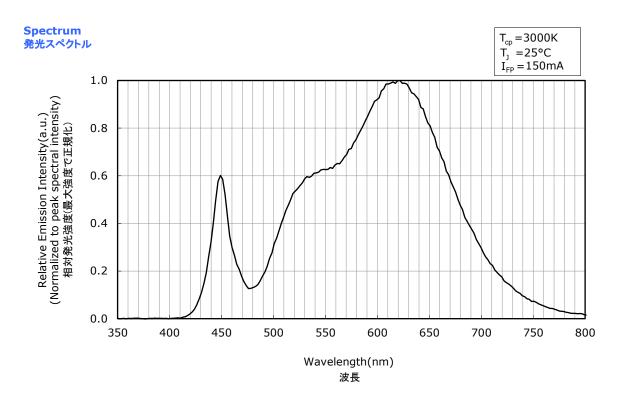


\* The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

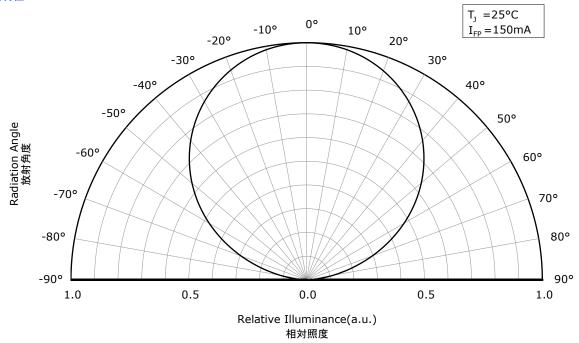
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-V4 No. STS-DA7-21169

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。





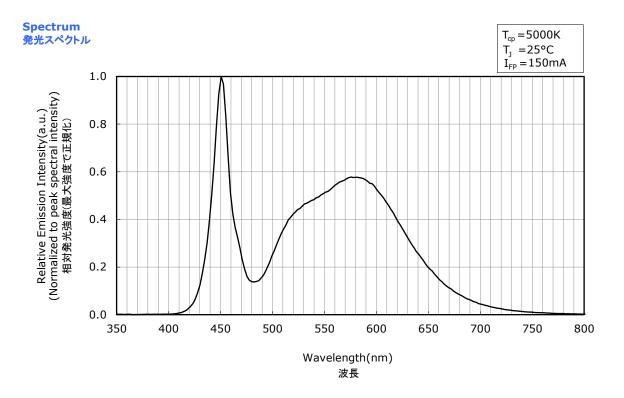


\* The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

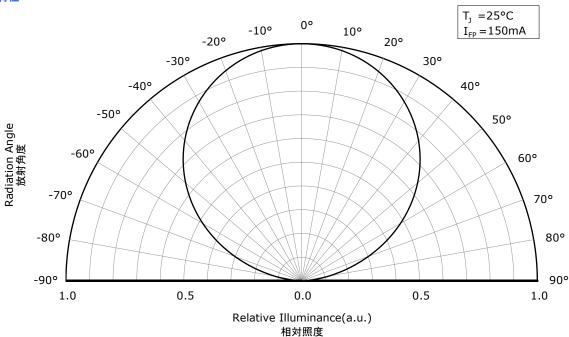
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14293A

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



### Directivity 指向特性

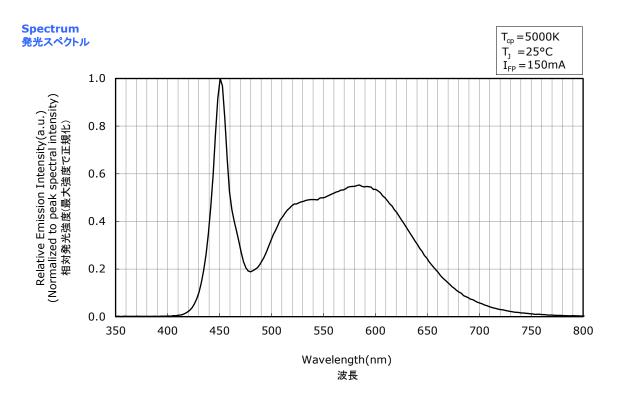


\* The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

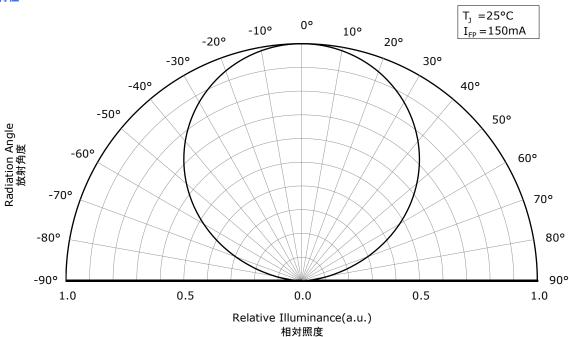
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14294A

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



### Directivity 指向特性

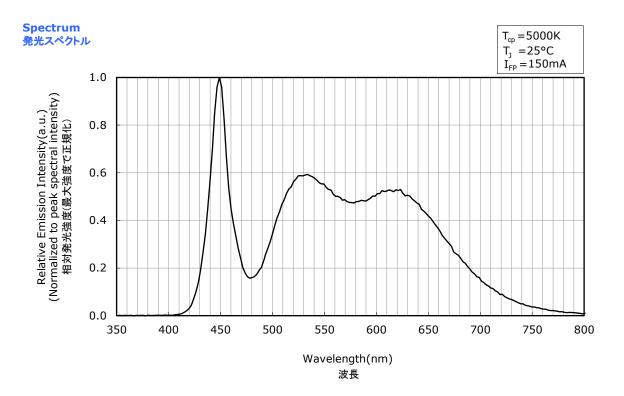


\* The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

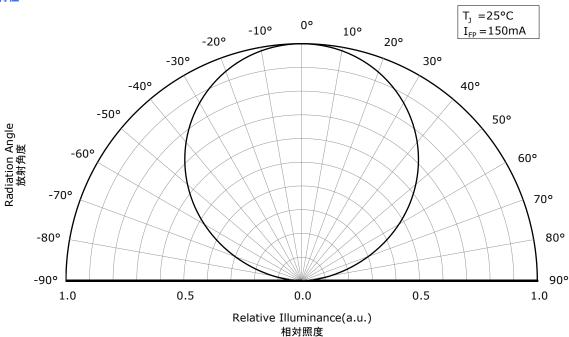
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14295A

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



### Directivity 指向特性

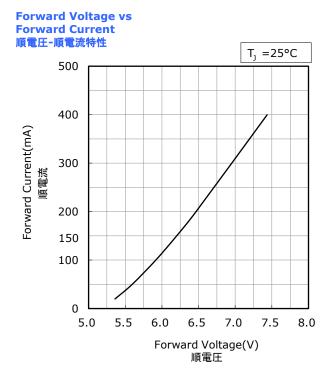


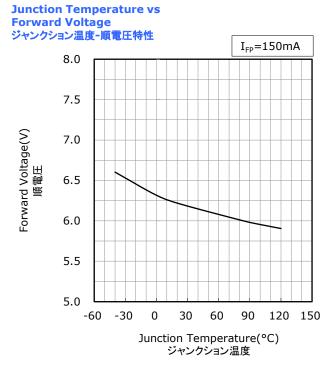
\* The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

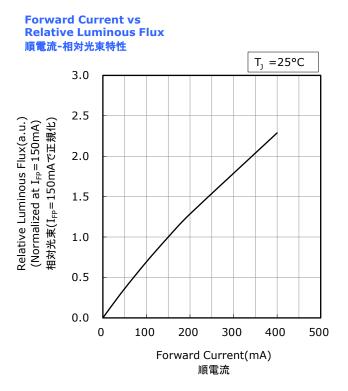
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

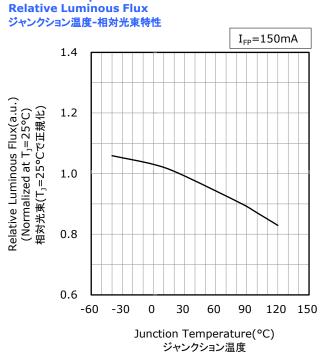
Part No. NF2W757GR-V4 No. STS-DA7-20365

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







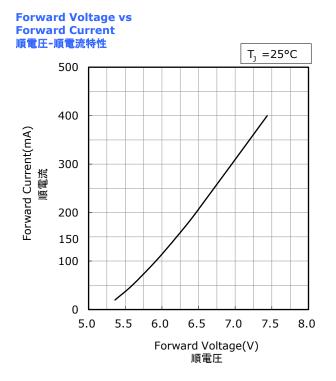


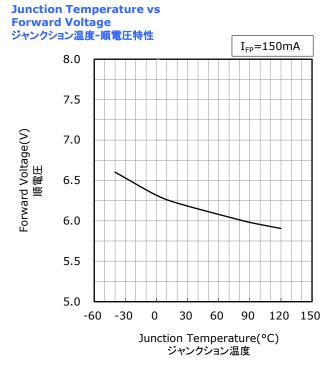
<sup>\*</sup> The graphs above show the characteristics for 1800K~4500K, R70 LEDs of this product. 本特性は色温度1800K~4500K、演色性ランクR70に対応しています。

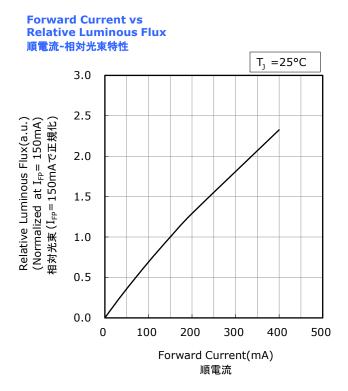
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

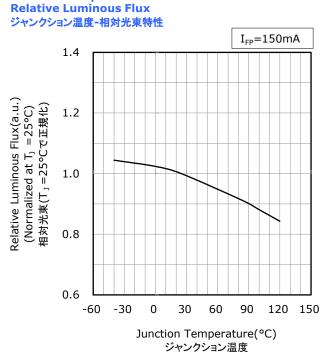
Part No. NF2W757GR-Vx No. STS-DA7-14297B

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。







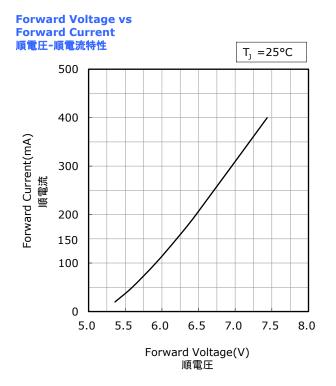


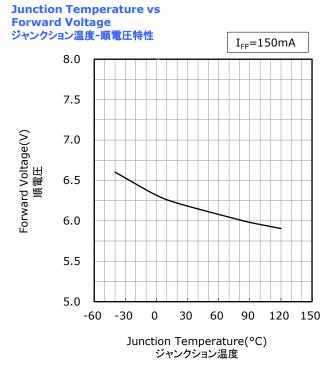
<sup>\*</sup> The graphs above show the characteristics for 2000K~4500K, R8000 LEDs of this product. 本特性は色温度2000K~4500K、演色性ランクR8000に対応しています。

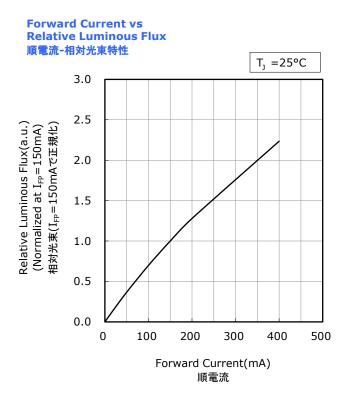
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

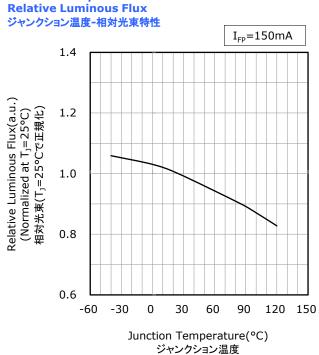
Part No. NF2W757GR-V4 No. STS-DA7-21170

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







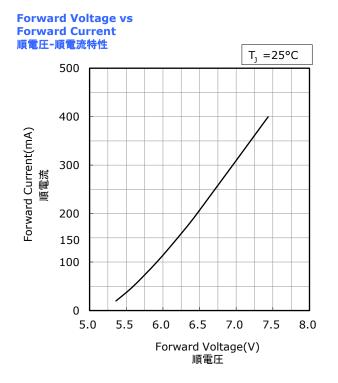


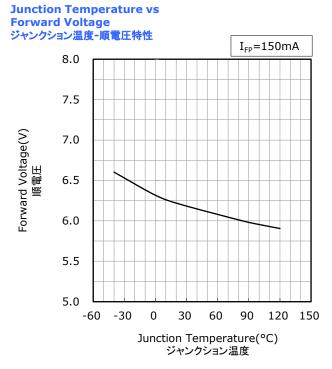
<sup>\*</sup> The graphs above show the characteristics for 1800K~4500K, R9050 LEDs of this product. 本特性は色温度1800K~4500K、演色性ランクR9050に対応しています。

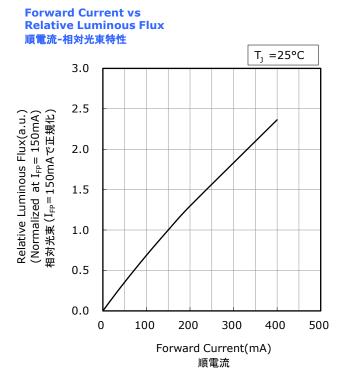
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

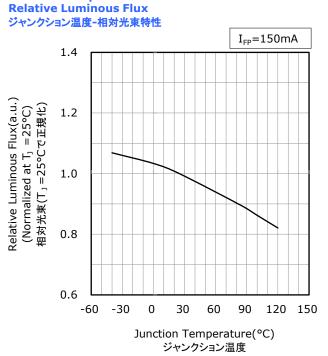
Part No. NF2W757GR-Vx No. STS-DA7-14299A

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。







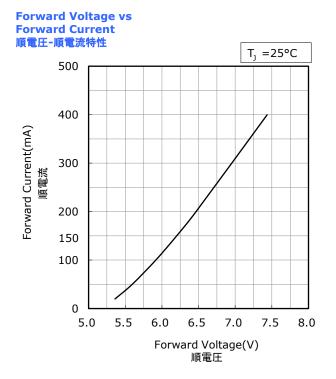


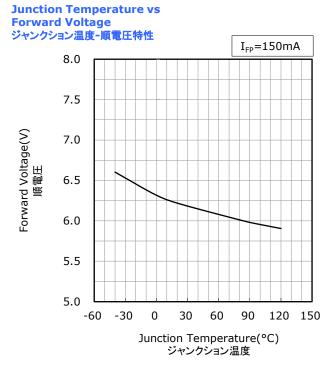
<sup>\*</sup> The graphs above show the characteristics for 5000K~6500K, R70 LEDs of this product. 本特性は色温度5000K~6500K、演色性ランクR70に対応しています。

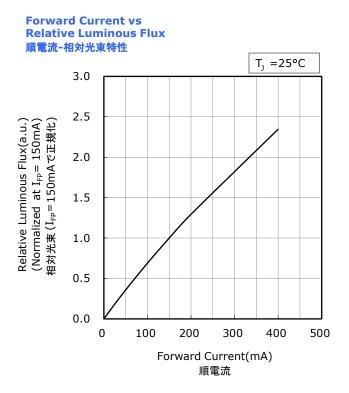
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

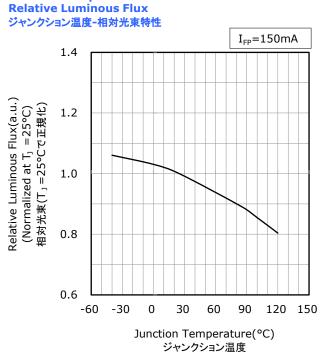
Part No. NF2W757GR-Vx No. STS-DA7-14300B

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。







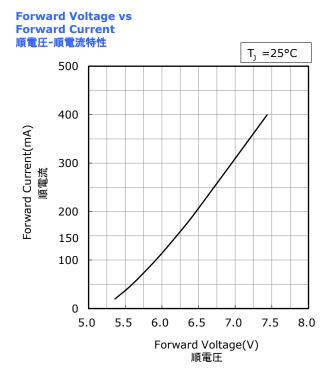


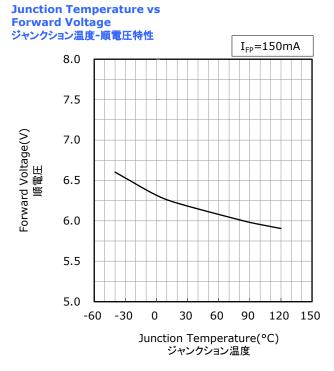
<sup>\*</sup> The graphs above show the characteristics for 5000K~6500K, R8000 LEDs of this product. 本特性は色温度5000K~6500K、演色性ランクR8000に対応しています。

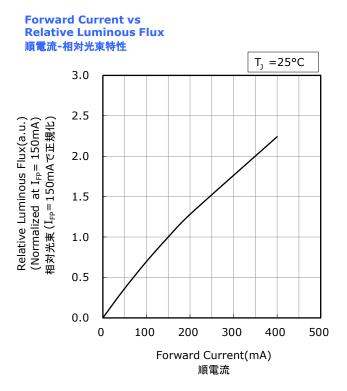
\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

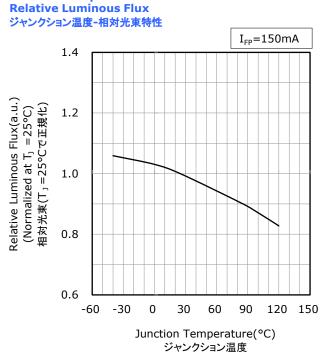
Part No. NF2W757GR-Vx No. STS-DA7-14301B

\* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。





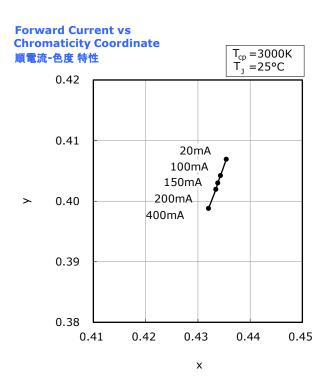


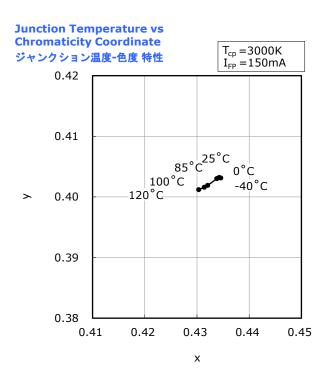


<sup>\*</sup> The graphs above show the characteristics for 5000K~6500K, R9050 LEDs of this product. 本特性は色温度5000K~6500K、演色性ランクR9050に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-V4 No. STS-DA7-20366

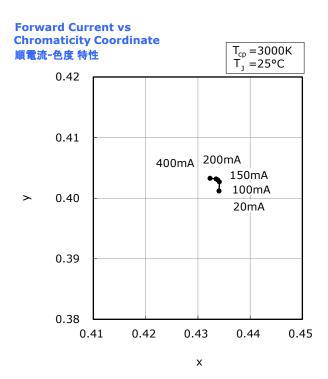


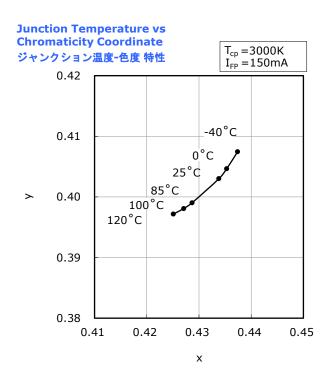


<sup>\*</sup> The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14303B

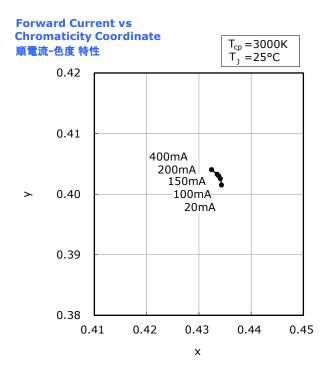


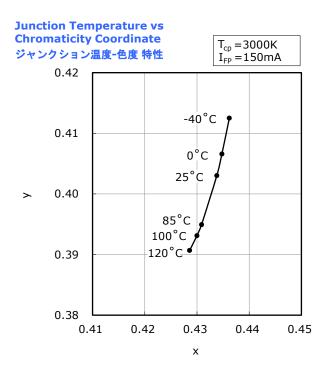


<sup>\*</sup> The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-V4 No. STS-DA7-21171

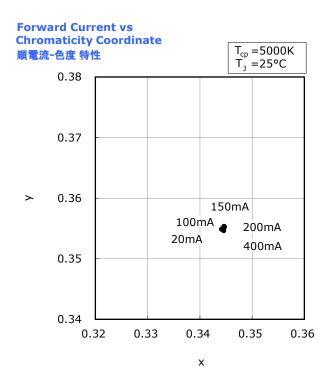


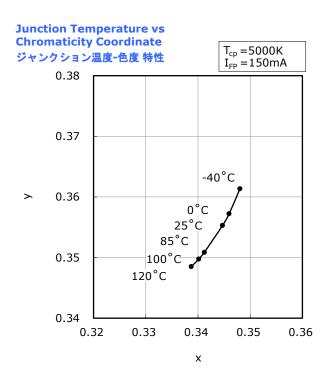


<sup>\*</sup> The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14305B

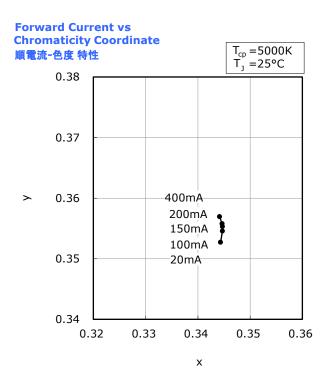


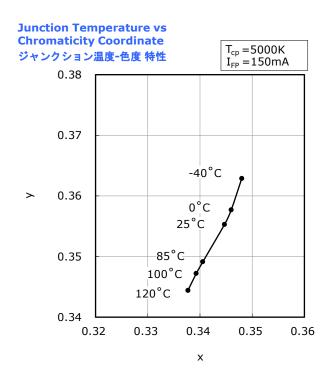


<sup>\*</sup> The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14306B

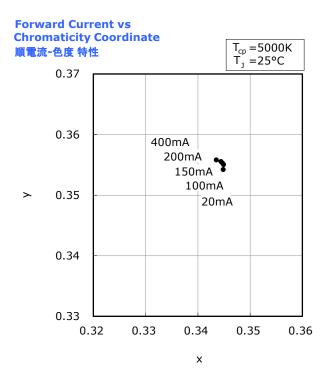


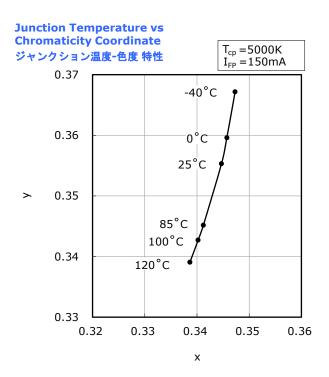


<sup>\*</sup> The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

\* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NF2W757GR-Vx No. STS-DA7-14307B





<sup>\*</sup> The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

# **RELIABILITY**

# (1) Tests and Results

Test	Reference Standard	Test Conditions	Test Duration	Failure Criteria #	Units Failed/Tested
Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701 300 301	T <sub>sld</sub> =260°C, 10sec, 2reflows, Precondition: 30°C, 70%RH, 168hr		#1	0/22
Solderability	JEITA ED-4701 303 303A	T <sub>sld</sub> =245±5°C, 5sec, Lead-free Solder(Sn-3.0Ag-0.5Cu)		#2	0/22
Temperature Cycle	JEITA ED-4701 100 105	-40°C(30min)~25°C(5min)~ 100°C(30min)~25°C(5min)	100cycles	#1	0/50
Moisture Resistance (Cyclic)	JEITA ED-4701 200 203	25°C~65°C~-10°C, 90%RH, 24hr per cycle	10cycles	#1	0/22
High Temperature Storage	JEITA ED-4701 200 201	T <sub>A</sub> =100°C	1000hours	#1	0/22
Temperature Humidity Storage	JEITA ED-4701 100 103	T <sub>A</sub> =60°C, RH=90%	1000hours	#1	0/22
Low Temperature Storage	JEITA ED-4701 200 202	T <sub>A</sub> =-40°C	1000hours	#1	0/22
Room Temperature Operating Life Condition 1		$T_A$ =25°C, $I_F$ =150mA Test board: See NOTES below	1000hours	#1	0/22
Room Temperature Operating Life Condition 2		$T_A=25$ °C, $I_F=200$ mA Test board: See NOTES below	500hours	#1	0/22
High Temperature Operating Life		T <sub>A</sub> =100°C, I <sub>F</sub> =85mA Test board: See NOTES below	1000hours	#1	0/22
Temperature Humidity Operating Life		$60$ °C, RH=90%, $I_F$ =150mA Test board: See NOTES below	500hours	#1	0/22
Low Temperature Operating Life		T <sub>A</sub> =-40°C, I <sub>F</sub> =150mA Test board: See NOTES below	1000hours	#1	0/22
Vibration	JEITA ED-4701 400 403	200m/s², 100~2000~100Hz, 4cycles, 4min, each X, Y, Z	48minutes	#1	0/22
Electrostatic Discharges	ANSI/ESDA/ JEDEC JS-001	HBM, 8kV, $1.5k\Omega$ , $100pF$ , $1pulse$ , alternately positive or negative		#1	0/22
Board Bending		1bend to a deflection of 2mm for 5±1sec		#3	0/22
Soldering Joint Shear Strength	JEITA ED-4702B 002 3	5N, 10±1sec		#1	0/22

### NOTES:

- 1) Test board: FR4 board thickness=1.6mm, copper layer thickness=0.07mm,  $R_{\theta JA} \approx 34$  °C/W The Board Bending is performed using an exclusive test board.
- 2) Measurements are performed after allowing the LEDs to return to room temperature.

# (2) Failure Criteria

١.	-/ :					
	Criteria #	Items	Conditions	Failure Criteria		
#		Forward Voltage(V <sub>F</sub> )	I <sub>F</sub> =150mA	>U.S.L.×1.1		
	#1	Luminous Flux(Φ <sub>ν</sub> )	I <sub>F</sub> =150mA	<l.s.l.×0.7< td=""></l.s.l.×0.7<>		
	#2	Solderability	-	Less than 95% solder coverage		
	#3	Appearance	-	The light emission is abnormal		

U.S.L. : Upper Specification Limit L.S.L. : Lower Specification Limit

# **CAUTIONS**

### (1) Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	≤30°C	≤90%RH	Within 1 Year from Delivery Date
	After Opening Aluminum Bag	≤30°C	≤70%RH	≤168hours
Baking		65±5°C	-	≥24hours

- The storage/packaging requirements for this LED are comparable to JEDEC Moisture Sensitivity Level (MSL) 3 or equivalent. Nichia used IPC/JEDEC STD-020 as a reference to rate the MSL of this LED.
- This LED uses a package that could absorb moisture; if the package absorbs moisture and is exposed to heat during soldering, it may cause the moisture to vaporize and the package to expand and the resulting pressure may cause internal delamination. This may cause the optical characteristics to degrade. To minimize moisture absorption in storage/transit, moisture-proof aluminum bags are used for the LEDs with a silica gel packet to absorb any air moisture in the bag. The silica gel beads turn blue to red as they absorb moisture.
- Once the moisture-proof aluminum bag is open, ensure that the LED is soldered to a PCB within the range of the conditions above. To store any remaining unused LEDs, use a hermetically sealed container with silica gel desiccants. Nichia recommends placing them back to the original moisture-proof bag and reseal it.
- If the "After Opening" storage time has been exceeded or any pink silica gel beads are found, ensure that the LED are baked before use. Baking should only be done once.
- The parts/materials (e.g. housing, gasket/seal, secondary lens, lens cover, thermal grease, etc.) used with the LED in the same assembly/system may release corrosive gases containing sulfur, halogens, etc. A light-up test, sufficient verifications, etc. must be performed at the finished product level (i.e. automotive headlamp, luminaire, etc.) prior to use taking into consideration the conditions/environments in which the finished product will actually be used to ensure that the expected performance for the finished product is maintained. See below for the detailed information.

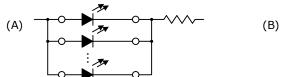
Issues that may be caused by corrosive gases containing sulfur, halogens, etc.:

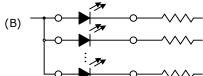
This LED has plated parts. If the LED is exposed to corrosive gases containing sulfur, halogens, etc., it may cause the plated surface to tarnish. If the gases penetrate the LED (e.g. emitting surface, package material, etc.), it may cause the surface of the plated parts inside the package to tarnish. In addition, it has been confirmed that if a silicone resin is used in the LED, the gases may accelerate degradation of the silicone resin. As a result, the optical characteristics may be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.); in the worst case, the circuit could become open causing a catastrophic failure (i.e. the LED not to illuminate). When determining the storage environment for the LED and/or selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that corrosive gases containing sulfur, halogens, etc. are not generated.

- To avoid condensation, the LEDs must not be stored in areas where temperature and humidity fluctuate greatly.
- Do not store the LEDs in a dusty environment.
- Do not expose the LEDs to direct sunlight and/or an environment over a long period of time where the temperature is higher than normal room temperature.

### (2) Directions for Use

• The circuit must be designed to ensure that the Absolute Maximum Ratings are not exceeded for each LED. The LEDs should be operated at a constant current per LED. In the case of operating at a constant voltage, Circuit B is recommended. If Circuit A is used, it may cause the currents flowing through the LEDs to vary due to the variation in the forward voltage characteristics of the LEDs on the circuit.





- This LED is designed to be operated at a forward current. Ensure that no voltage is applied to the LED in the forward/reverse direction while the LED is off. If the LEDs are used in an environment where reverse voltages are applied to the LED continuously, it may cause electrochemical migration to occur causing the LED to be damaged. When not in use for a long period of time, the system's power should be turned off to ensure that there are no issues/damage.
- To stabilize the LED characteristics while in use, Nichia recommends that the LEDs are operated at currents ≥ 10% of the sorting current.
- Ensure that transient excessive voltages (e.g. lightning surge) are not applied to the LEDs.
- If the LEDs are used for outdoor applications, ensure that necessary measures are taken (e.g. protecting the LEDs from water/salt damage and high humidity).

# (3) Handling Precautions

- Do not handle the LEDs with bare hands:
  - this may contaminate the LED surface and have an effect on the optical characteristics,
  - this may cause the LED to deform and/or the wire to break causing a catastrophic failure (i.e. the LED not to illuminate).
- Ensure that when handling the LEDs with tweezers, excessive force is not applied to the LED. Otherwise, it may cause damage to the resin (e.g. cut, scratch, chip, crack, delamination and deformation) and the wire to break causing a catastrophic failure (i.e. the LED not to illuminate).
- Dropping may cause damage to the LED (e.g. deformation).
- Do not stack assembled PCBs together. Otherwise, it may cause damage to the resin (e.g. cut, scratch, chip, crack, delamination and deformation) and the wire to break causing a catastrophic failure (i.e. the LED not to illuminate).
- CRI Rank R9050 LEDs in this specification use materials that contain halogen-based compounds; the halogen element found in these materials will not affect the LEDs when the LEDs are used under the conditions detailed in this specification. The other CRI ranks in this specification do not use these materials.
- Due to the variation in the amount of the reflective material (white resin) that is coating the protection device, the area around the protection device may appear to be a black spot; this will not affect the characteristics of the LED. Do not use the location of the protection device to determine the polarity of the LED; use the cathode mark.

### (4) Design Consideration

- If the LEDs are soldered to a PCB and the PCB assembly is bent (e.g. PCB depanding process), it may cause the LED package to break. The PCB layout should be designed to minimize the mechanical stress on the LEDs when the PCB assembly is bent/warped.
- The amount of mechanical stress exerted on the LED from depaneling may vary depending on the LED position/orientation on the PCB assembly (e.g. especially in areas near V-groove scores). The PCB layout should be designed to minimize the mechanical stress on the LEDs when the PCB is separated into individual PCB assemblies.
- To separate a PCB populated with the LEDs, use a specially designed tool. Do not break the PCB by hand.
- The parts/materials (e.g. housing, gasket/seal, secondary lens, lens cover, thermal grease, etc.) used with the LED in the same assembly/system may release corrosive gases containing sulfur, halogens, etc., and/or volatile organic compounds (VOCs). A light-up test, sufficient verifications, etc. must be performed at the finished product level (i.e. automotive headlamp, luminaire, etc.) prior to use taking into consideration the conditions/environments in which the finished product will actually be used to ensure that the expected performance for the finished product is maintained. See below for the detailed information.

Issues that may be caused by corrosive gases containing sulfur, halogens, etc.:

This LED has plated parts. If the LED is exposed to corrosive gases containing sulfur, halogens, etc., it may cause the plated surface to tarnish. If the gases penetrate the LED (e.g. emitting surface, package material, etc.), it may cause the surface of the plated parts inside the package to tarnish. In addition, it has been confirmed that if a silicone resin is used in the LED, the gases may accelerate degradation of the silicone resin. As a result, the optical characteristics may be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.); in the worst case, the circuit could become open causing a catastrophic failure (i.e. the LED not to illuminate). When determining the storage environment for the LED and/or selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that corrosive gases containing sulfur, halogens, etc. are not generated.

### Issues that may be caused by VOCs:

If VOCs that have been released from the parts/materials and/or organic additives used with the LED in the finished product penetrate into the LED and remain inside the LED, the VOCs can discolor after being exposed to heat and/or photon energy. This may cause the optical characteristics to be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.). This adverse effect may be improved by ventilating the environment (i.e. the LED is not used in a hermetically sealed environment) to prevent the VOCs from remaining inside the LED. When selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that there are no issues with the substances found in those parts/materials and/or that the expected performance for the finished product is maintained by performing a light-up test, sufficient verifications etc. taking into consideration the conditions/environments in which the finished product will actually be used.

• The characteristics of the LEDs (e.g. chromaticity, color rendering index, etc.) will vary depending on how the LEDs are designed into the application (e.g. secondary lens, luminaire cover/housing, etc. for ease of dissipation), how they were assembled, under what conditions/environments they are used (e.g. operating current/temperature, etc.), and how long they have been used (e.g. storage/operating hours, etc.). To ensure that there are no issues (e.g. deviations/changes in the characteristics, etc.) with the chosen application, perform a sufficient verification prior to use.

### (5) Electrostatic Discharge (ESD)

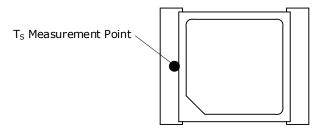
- This LED is sensitive to transient excessive voltages (e.g. ESD, lightning surge). If this excessive voltage occurs in the circuit, it may cause the LED to be damaged causing issues (e.g. the LED to become dimmer or not to illuminate [i.e. catastrophic failure]). Ensure that when handling the LEDs, necessary measures are taken to protect them from an ESD discharge. The following examples are recommended measures to eliminate the charge:
  - Grounded wrist strap, ESD footwear, clothes, and floors
  - Grounded workstation equipment and tools
  - ESD table/shelf mat made of conductive materials
- Ensure that all necessary measures are taken to prevent the LEDs from being exposed to transient excessive voltages (e.g. ESD, lightning surge):
  - tools (e.g. soldering irons), jigs, and machines that are used are properly grounded
  - appropriate ESD materials/equipment are used in the work area
  - the system/assembly is designed to provide ESD protection for the LEDs.
- If the tool/equipment used is an insulator (e.g. glass cover, plastic, etc.), ensure that necessary measures have been taken to protect the LED from transient excessive voltages (e.g. ESD). The following examples are recommended measures to eliminate the charge:
  - Dissipating static charge with conductive materials
  - Preventing charge generation with moisture
  - Neutralizing the charge with ionizers
- To detect if an LED was damaged by transient excess voltages (i.e. an ESD event during the system's assembly process), perform
  a characteristics inspection (e.g. forward voltage measurement, light-up test) at low current (≤1mA).
- Failure Criteria: V<sub>F</sub><4.0V at I<sub>F</sub>=0.5mA

If the LED is damaged by transient excess voltages (e.g. ESD), it will cause:

- the Forward Voltage (V<sub>F</sub>) to decrease
- the LED not to illuminate at a low current

### (6) Thermal Management

- When using the LEDs for the chosen application, it is necessary to consider the heat generated from the LEDs during operation. The increase in the temperature of an LED chip while in operation may vary depending on variations in the thermal resistance, the thermal resistance of the chosen PCB and the density of LEDs in the system/assembly. The Absolute Maximum Junction Temperature (T<sub>J</sub>) must not be exceeded under any circumstances; ensure that heat is not concentrated in an area and is properly managed in the system/assembly.
- The operating current should be determined by considering the temperature conditions surrounding the LED (i.e. T<sub>A</sub>). Ensure that when operating the LED, proper measures are taken to dissipate the heat.
- The following equations can be used to calculate the LED temperature (i.e. T<sub>1</sub>) once the saturation temperature at the junction has been reached.
  - 1)  $T_J = T_A + R_{\theta JA} \cdot W$  2)  $T_J = T_S + R_{\theta JS} \cdot W$ \* $T_J = LED$  Junction Temperature: °C  $T_A = Ambient$  Temperature: °C  $T_S = Soldering$  Temperature (Cathode Side): °C  $R_{\theta JA} = Thermal$  Resistance from Junction to Ambient: °C/W  $R_{\theta JS} = Thermal$  Resistance from Junction to  $T_S$  Measurement Point: °C/W W = Input Power( $I_F \times V_F$ ): W



### (7) Cleaning

- Do not wipe/clean the LEDs with a damp cloth soaked in water or solvents (e.g. benzine, thinner, etc.).
- If required, use isopropyl alcohol (IPA). If water or other solvent is used, it may cause issues. Before using the solvent, ensure that sufficient verification is performed to ensure that the solvent does not adversely affect the LEDs. In addition, the use of CFCs such as Freon is heavily regulated.
- When a foreign substance (e.g. dust, debris, loose materials, etc.) adheres to the LEDs, wipe it off with a damp well-squeezed cloth that was soaked only in isopropyl alcohol (IPA).
- Do not wipe the emitting surface. Otherwise, it may result in excessive pressure to the emitting surface causing issues (e.g. wire to deform, the encapsulating resin to become damaged, the color to change, etc.). If wiping the emitting surface is necessary, ensure that sufficient preliminary verification is performed to ensure that there are no issues; wipe the emitting surface at the customer's risk.
- Do not clean the LEDs with an ultrasonic cleaner. If cleaning must be done, ensure that sufficient verification is performed by using a finished assembly with LEDs to determine cleaning conditions (e.g. ultrasonic power, LED position on the PCB assembly) that do not cause an issue.

### (8) Eye Safety

- There may be two important international specifications that should be noted for safe use of the LEDs: IEC 62471:2006

  Photobiological safety of lamps and lamp systems and IEC 60825-1:2001 (i.e. Edition 1.2) Safety of Laser Products Part 1:

  Equipment Classification and Requirements. Ensure that when using the LEDs, there are no issues with the following points:
  - LEDs have been removed from the scope of IEC 60825-1 since IEC 60825-1:2007 (i.e. Edition 2.0) was published. However, depending on the country/region, there are cases where the requirements of the IEC 60825-1:2001 specifications or equivalent must be adhered to.
  - LEDs have been included in the scope of IEC 62471:2006 since the release of the specification in 2006.
  - Most Nichia LEDs will be classified as the Exempt Group or Risk Group 1 according to IEC 62471:2006. However, in the case of high-power LEDs containing blue wavelengths in the emission spectrum, there are LEDs that will be classified as Risk Group 2 depending on the characteristics (e.g. radiation flux, emission spectrum, directivity, etc.)
  - If the LED is used in a manner that produces an increased output or with an optic to collimate the light from the LED, it may cause damage to the human eye.
- If an LED is operated in a manner that emits a flashing light, it may cause health issues (e.g. visual stimuli causing eye discomfort).

  The system should be designed to ensure that there are no harmful effects on the human body.

### (9) Miscellaneous

- Nichia warrants that the discrete LEDs will meet the requirements/criteria as detailed in the Reliability section within this specification. If the LEDs are used under conditions/environments deviating from or inconsistent with those described in this specification, the resulting damage and/or injuries will not be covered by this warranty.
- Nichia warrants that the discrete LEDs manufactured and/or supplied by Nichia will meet the requirements/criteria as detailed in the Reliability section within this specification; it is the customer's responsibility to perform sufficient verification prior to use to ensure that the lifetime and other quality characteristics required for the intended use are met.
- The applicable warranty period is one year from the date that the LED is delivered. In the case of any incident that appears to be in breach of this warranty, the local Nichia sales representative should be notified to discuss instructions on how to proceed while ensuring that the LED in question is not disassembled or removed from the PCB if it has been attached to the PCB. If a breach of this warranty is proved, Nichia will provide the replacement for the non-conforming LED or an equivalent item at Nichia's discretion. FOREGOING ARE THE EXCLUSIVE REMEDIES AVAILABLE TO THE CUSTOMER IN RESPECT OF THE BREACH OF THE WARRANTY CONTAINED HEREIN, AND IN NO EVENT SHALL NICHIA BE RESPONSIBLE FOR ANY INDRECT, INCIDENTAL OR CONSEQUENTIAL LOSSES AND/OR EXPENSES (INCLUDING LOSS OF PROFIT) THAT MAY BE SUFFERED BY THE CUSTOMER ARISING OUT OF A BREACH OF THE WARRANTY.
- NICHIA DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE.
- This LED is intended to be used for general lighting, household appliances, electronic devices (e.g. mobile communication devices); it is not designed or manufactured for use in applications that require safety critical functions (e.g. aircraft, automobiles, combustion equipment, life support systems, nuclear reactor control system, safety devices, spacecraft, submarine repeaters, traffic control equipment, trains, vessels, etc.). If the LEDs are planned to be used for these applications, unless otherwise detailed in the specification, Nichia will neither guarantee that the LED is fit for that purpose nor be responsible for any resulting property damage, injuries and/or loss of life/health. This LED does not comply with IATF 16949 and is not intended for automotive applications.
- The customer will not reverse engineer, disassemble or otherwise attempt to extract knowledge/design information from the LED.
- All copyrights and other intellectual property rights in this specification in any form are reserved by Nichia or the right holders who have granted Nichia permission to use the content. Without prior written permission from Nichia, no part of this specification may be reproduced in any form or by any means.
- Both the customer and Nichia will agree on the official specifications for the supplied LEDs before any programs are officially launched. Without this agreement in writing (i.e. Customer Specific Specification), changes to the content of this specification may occur without notice (e.g. changes to the foregoing specifications and appearance, discontinuation of the LEDs, etc.).